

SN54HC365, SN74HC365 HEX BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

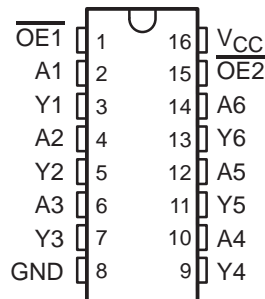
SCLS308D – JANUARY 1996 – REVISED OCTOBER 2003

- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Drive Bus Lines, Buffer-Memory Address Registers, or Drive Up To 15 LSTTL Loads
- True Outputs
- Low Power Consumption, 80- μ A Max I_{CC}
- Typical $t_{pd} = 10$ ns
- ± 6 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max

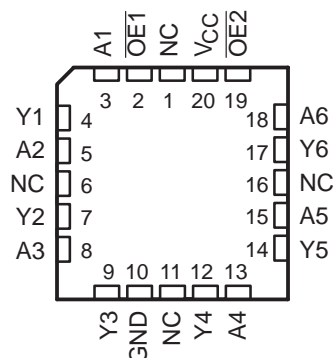
description/ordering information

These hex buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The 'HC365 devices contain six independent buffers/drivers with dual-gated output-enable ($\overline{OE1}$ and $\overline{OE2}$) inputs. When $\overline{OE1}$ and $\overline{OE2}$ are both low, the devices pass noninverted data from the A inputs to the Y outputs. If either (or both) output-enable terminal(s) is high, the outputs are in the high-impedance state.

SN54HC365 . . . J OR W PACKAGE
SN74HC365 . . . D, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54HC365 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 25	SN74HC365N	SN74HC365N
	SOIC – D	Tube of 40	SN74HC365D	HC365
		Reel of 2500	SN74HC365DR	
		Reel of 250	SN74HC365DT	
	SOP – NS	Reel of 2000	SN74HC365NSR	HC365
	TSSOP – PW	Reel of 90	SN74HC365PW	HC365
Reel of 2000		SN74HC365PWR		
Reel of 250		SN74HC365PWT		
-55°C to 125°C	CDIP – J	Tube of 25	SNJ54HC365J	SNJ54HC365J
	CFP – W	Tube of 150	SNJ54HC365W	SNJ54HC365W
	LCCC – FK	Tube of 55	SNJ54HC365FK	SNJ54HC365FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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 **TEXAS
INSTRUMENTS**

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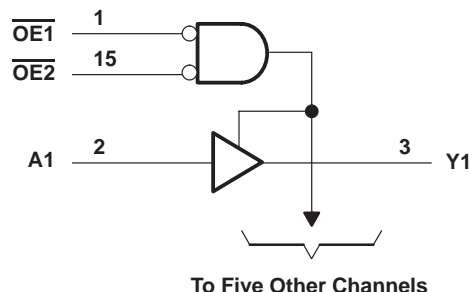
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FUNCTION TABLE
(each buffer/driver)

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
H	X	X	Z
X	H	X	Z
L	L	H	H
L	L	L	L

logic diagram (positive logic)



Pin numbers shown are for the D, J, N, NS, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	± 20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 35 mA
Continuous current through V_{CC} or GND	± 70 mA
Package thermal impedance, θ_{JA} (see Note 2):	
D package	73°C/W
N package	67°C/W
NS package	64°C/W
PW package	108°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

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recommended operating conditions (see Note 3)

		SN54HC365			SN74HC365			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V		1.5	1.5		V	
		V _{CC} = 4.5 V		3.15	3.15			
		V _{CC} = 6 V		4.2	4.2			
V _{IL}	Low-level input voltage	V _{CC} = 2 V			0.5	0.5	V	
		V _{CC} = 4.5 V			1.35	1.35		
		V _{CC} = 6 V			1.8	1.8		
V _I	Input voltage	0		V _{CC}	0	V _{CC}	V	
V _O	Output voltage	0		V _{CC}	0	V _{CC}	V	
Δt/Δv	Input transition rise/fall time	V _{CC} = 2 V			1000	1000	ns	
		V _{CC} = 4.5 V			500	500		
		V _{CC} = 6 V			400	400		
T _A	Operating free-air temperature	-55		125	-40	85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC}	T _A = 25°C			SN54HC365		SN74HC365		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -20 μA	2 V	1.9	1.998		1.9	1.9	V		
			4.5 V	4.4	4.499		4.4	4.4			
			6 V	5.9	5.999		5.9	5.9			
		I _{OH} = -6 mA	4.5 V	3.98	4.3		3.7	3.84			
		I _{OH} = -7.8 mA	6 V	5.48	5.8		5.2	5.34			
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 μA	2 V		0.002	0.1		0.1	0.1	V	
			4.5 V		0.001	0.1		0.1	0.1		
			6 V		0.001	0.1		0.1	0.1		
		I _{OL} = 6 mA	4.5 V		0.17	0.26		0.4	0.33		
		I _{OL} = 7.8 mA	6 V		0.15	0.26		0.4	0.33		
I _I	V _I = V _{CC} or 0		6 V		±0.1	±100		±1000	±1000	nA	
I _{OZ}	V _O = V _{CC} or 0		6 V		±0.01	±0.5		±10	±5	μA	
I _{CC}	V _I = V _{CC} or 0, I _O = 0		6 V			8		160	80	μA	
C _i			2 V to 6 V		3	10		10	10	pF	



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switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			SN54HC365		SN74HC365		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A	Y	2 V		50	95	145	120	ns		
			4.5 V		12	19	29	24			
			6 V		10	16	25	20			
t _{en}	\overline{OE}	Y	2 V		100	190	285	238	ns		
			4.5 V		26	38	57	48			
			6 V		21	32	48	41			
t _{dis}	\overline{OE}	Y	2 V		50	175	265	240	ns		
			4.5 V		21	35	53	48			
			6 V		19	30	45	41			
t _t		Any	2 V		28	60	90	75	ns		
			4.5 V		8	12	18	15			
			6 V		6	10	15	13			

switching characteristics over recommended operating free-air temperature range, $C_L = 150$ pF (unless otherwise noted) (see Figure 1)

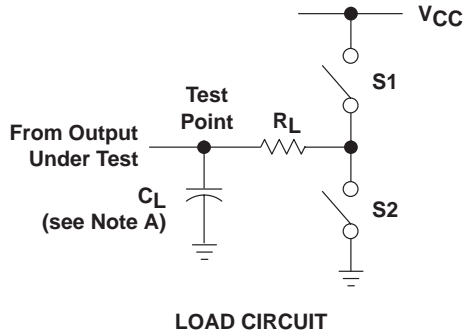
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			SN54HC365		SN74HC365		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A	Y	2 V		70	120	180	150	ns		
			4.5 V		17	24	36	30			
			6 V		14	20	31	25			
t _{en}	\overline{OE}	Y	2 V		140	230	345	285	ns		
			4.5 V		30	46	69	57			
			6 V		28	39	59	48			
t _t		Any	2 V		45	210	315	265	ns		
			4.5 V		17	42	63	53			
			6 V		13	36	53	45			

operating characteristics, T_A = 25°C

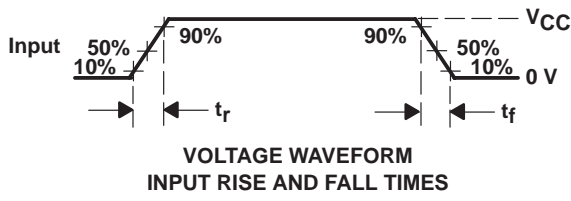
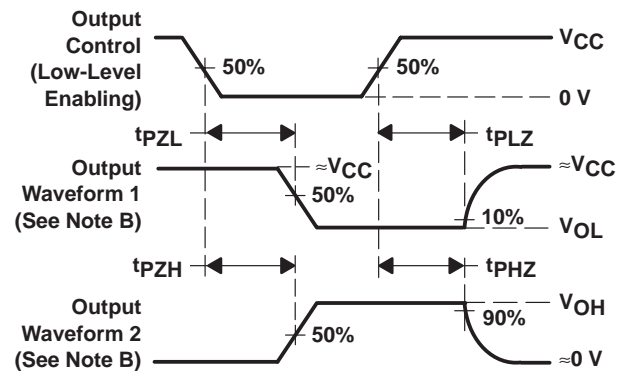
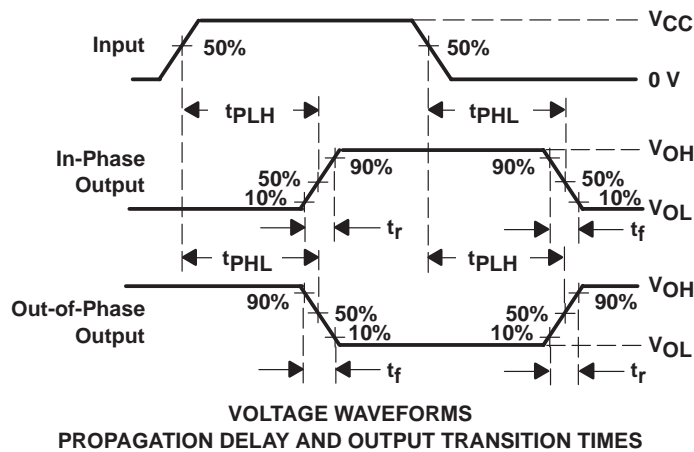
PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance per buffer/driver	No load	35	pF



PARAMETER MEASUREMENT INFORMATION



PARAMETER	R_L	C_L	S1	S2	
t_{en}	t_{PZH}	1 k Ω	50 pF or 150 pF	Open	Closed
	t_{PZL}			Closed	Open
t_{dis}	t_{PHZ}	1 k Ω	50 pF	Open	Closed
	t_{PLZ}			Closed	Open
t_{pd} or t_t	--	50 pF or 150 pF	Open	Open	



- NOTES: A. C_L includes probe and test-fixture capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
 D. The outputs are measured one at a time with one input transition per measurement.
 E. t_{PLH} and t_{PHL} are the same as t_{pd} .
 F. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 G. t_{PZL} and t_{PZH} are the same as t_{en} .

Figure 1. Load Circuit and Voltage Waveforms

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



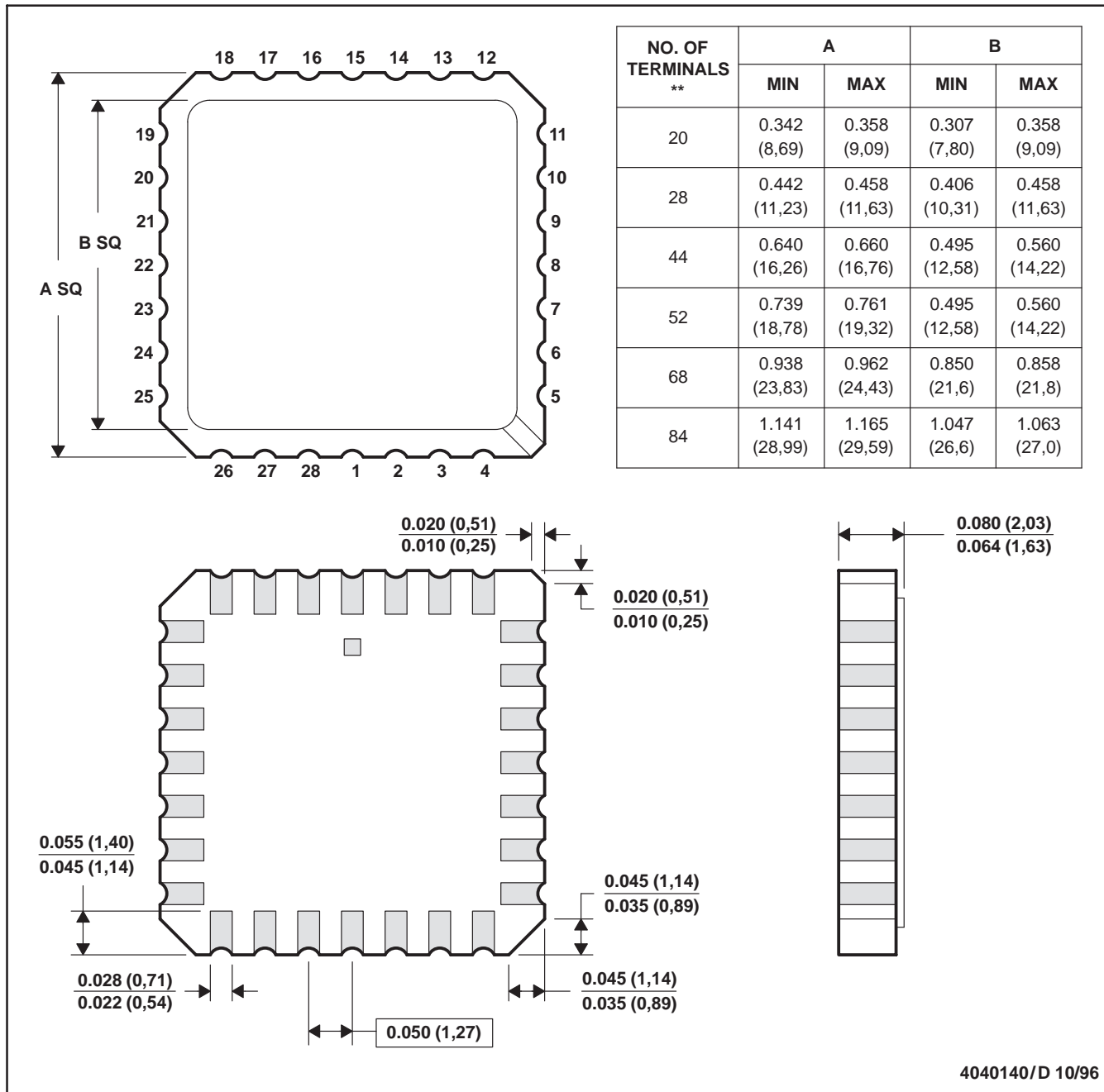
4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

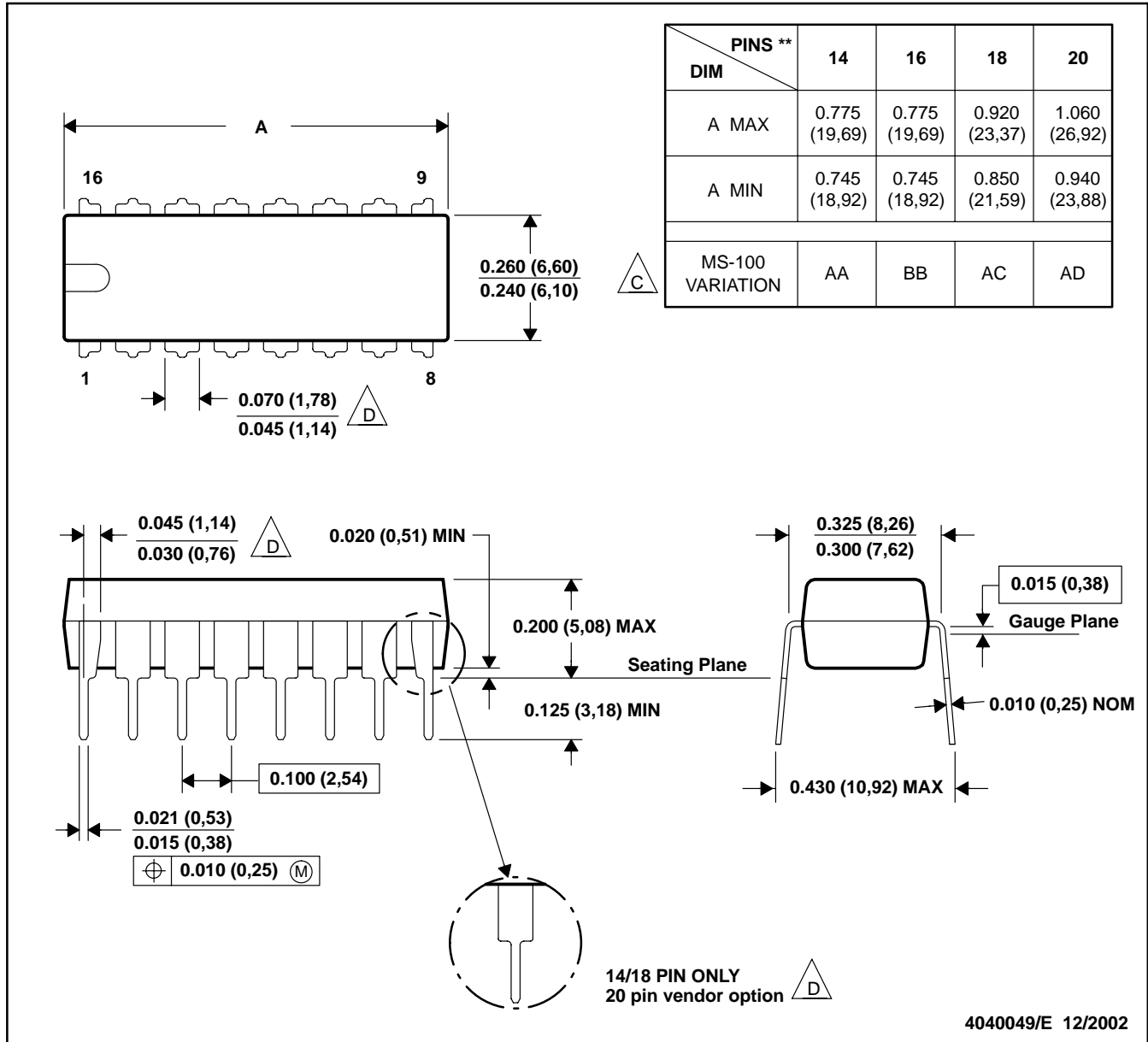


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

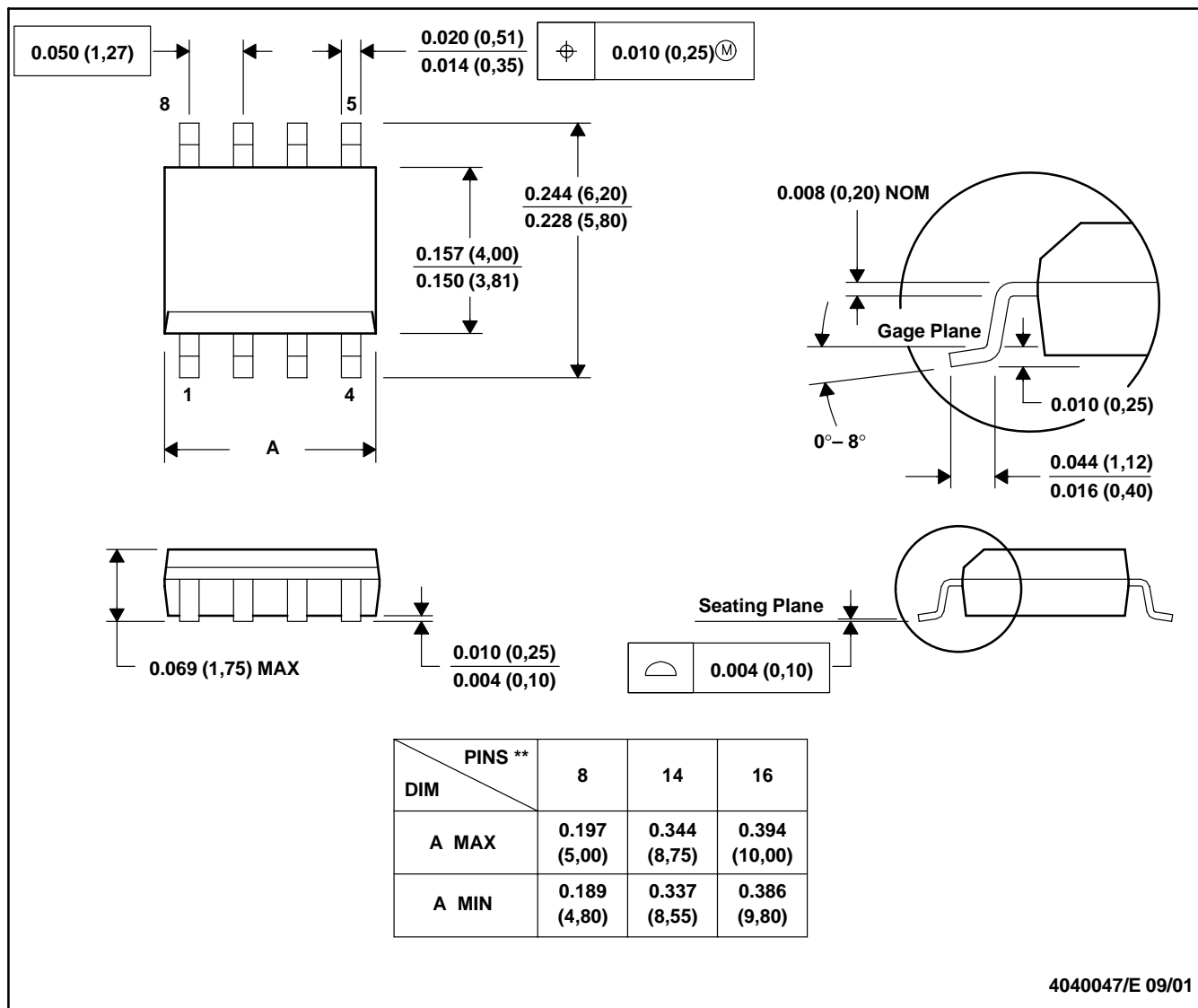


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 D The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-012

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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